

Date: July 2019
Rev: VIII
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.28
Pot Life: 28 Days
Shelf Life- Bulk: One year at -40°C
Shelf Life- Syringe: Six months at -40°C

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 125°C / 1 Hour

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® TD1001-67 is a soft single component, thermally conductive, electrically insulating epoxy. It is a more compliant version of EPO-TEK® TD1001.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
 Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	White		
* Consistency:	Smooth paste		
* Viscosity (23°C) @ 5 rpm:	10,000-20,000	cPs	
Thixotropic Index:	1.9		
* Glass Transition Temp:	≥ 1	°C	(Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -40-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):			
Below Tg:	57	x 10 ⁻⁶	in/in°C
Above Tg:	272	x 10 ⁻⁶	in/in°C
Shore A Hardness:	60		
Lap Shear @ 23°C:	1,356	psi	
Die Shear @ 23°C:	≥ 2.5	Kg	> 889 psi
Degradation Temp:	340	°C	
Weight Loss:			
@ 200°C:	< 0.05	%	
@ 250°C:	0.35	%	
@ 300°C:	1.44	%	
Suggested Operating Temperature:	< 275	°C	(Intermittent)
Storage Modulus:	54,539	psi	
* Particle Size:	≤ 20	microns	

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	0.5	W/mK
Volume Resistivity @ 23°C:	≥ 8 x 10 ¹¹	Ohm-cm
Dielectric Constant (1KHz):	3.93	
Dissipation Factor (1KHz):	0.0688	

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.

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EPO-TEK® TD1001-67 Advantages & Suggested Application Notes:

- Optimal for stress relief applications with its low Tg and long pot life
- Suitable for bonding ferrite cores in power devices
- Excellent adhesion to PCBs. Ceramics, most metals and lead frames
- Suggested applications:
 - Semiconductor-
 - IC packaging on lead frame or FR4 PCB
 - Low stress die attach for die greater than 500 mil x 500 mil
 - Electronics-
 - Bonding large Cu and Al heat sinks
 - Staking SMDs to PCB and other substrates
 - Other-
 - LED thermal management
 - Heat sinking sensitive laser diode packages
 - Fiber optic component packaging and assembly

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